BGA REWORK SYSTEMS

SEAMARK ZM-R8650C

Fully Automatic Hot Air BGA Rework Station

Fully Automatic Desoldering and Mounting | PCB up to 660 × 600 mm | ±0.025 mm Alignment | 8 Temperature Inputs | MES Ready



OVERVIEW

The **Seamark ZM-R8650C** is a fully automatic hot air BGA rework station with optical alignment for large boards such as 5G base station, server and industrial control boards up to 660 × 600 mm. It handles components from 1 × 1 mm chips to 100 × 100 mm modules, from recognition and alignment to placement, soldering and desoldering.

A servo motion system and 2-megapixel vision align parts with ±0.025 mm accuracy, so results do not depend on operator skill. Top and bottom convection hot air zones and a 16 kW infrared preheating zone, each with its own K-type thermocouple loop, keep high-thermal-mass boards flat and fully reflowed.

KEY FEATURES

Fully automatic process

automatic optical mounting and desoldering; the operator selects the profile and presses start

Three independently controlled zones

convection hot air top and bottom, large-area bottom heater for big BGAs, medium-wave ceramic infrared preheating plates made in Germany

Precise temperature control

K-type thermocouples, dynamic PID multi-loop closed-loop control and selective reflow profile, ±1 °C; 8 external sensors for profile recording and analysis

Traceability and Industry 4.0

temperature profile analysis per serial number (S/N); optional software link to SAP, ERP and MES

Full ESD protection

ESD-safe design with integrated ionising air blower for sensitive BGA, GPU and FPGA devices

Fast changeover

L-groove and universal fixtures, custom fixtures for irregular boards

TYPICAL APPLICATIONS

5G base station and telecom boards, server blades and motherboards, industrial control boards and other high-thermal-mass PCBs in EMS production, including medical, aerospace and automotive electronics.

TECHNICAL SPECIFICATIONS

Power Supply	AC 380 V ±10%, 50/60 Hz
Power	22 kW total (upper zone 2 kW, lower zone 2 kW, preheating zone 16 kW, other 2 kW)
PCB Size	Max. 660 × 600 mm, min. 10 × 10 mm
BGA Chip Size	Max. 100 × 100 mm, min. 1 × 1 mm
IR Zone Size	645 × 524 mm
Motion Control	X / Y / Z
External Temperature Sensors	8 pcs
Control System	Industrial PC + servo motion control
Display	24" HD monitor
Alignment System	2-megapixel optical vision alignment
Vacuum Adsorption	Fully automatic
Alignment Accuracy	±0.025 mm
Temperature Control	K-type thermocouple, closed loop, independent control per zone, ±1 °C
Feeding Device	Semi-automatic
Positioning	L-groove and universal fixture (custom fixtures for irregular boards)
Dimensions (L×W×H)	1235 × 1557 × 1850 mm
Net Weight	993.5 kg

Configuration, demo and quotation

InterElectronic is the Seamark partner for Hungary and Central Europe: application advice, sample tests, installation, training and service.

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Specifications according to Seamark. Subject to change without notice.